



Material Content Data Sheet



Sales Product Name		SAK-TC1766-192F80HL BD		Issued		29. August 2013		
MA#		MA000945090						
Package		PG-LQFP-176-14		Weight*		2045.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	36.463	1.78	1.78	17828	17828
leadframe	non noble metal	magnesium	7439-95-4	0.746	0.04		365	
	inorganic material	silicon	7440-21-3	3.234	0.16		1581	
	non noble metal	nickel	7440-02-0	14.926	0.73		7298	
wire	non noble metal	copper	7440-50-8	478.622	23.40	24.33	234021	243265
	noble metal	gold	7440-57-5	3.526	0.17	0.17	1724	1724
	encapsulation	organic material	carbon black	1333-86-4	4.452	0.22		2177
encapsulation	plastics	epoxy resin	-	136.527	6.68		66754	
	inorganic material	silicondioxide	60676-86-0	1343.008	65.66	72.56	656662	725593
leadfinish	non noble metal	tin	7440-31-5	15.144	0.74	0.74	7405	7405
plating	noble metal	silver	7440-22-4	2.988	0.15	0.15	1461	1461
glue	plastics	epoxy resin	-	1.393	0.07		681	
	noble metal	silver	7440-22-4	4.178	0.20	0.27	2043	2724
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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